

Photopolymerizable resinous composition

Abstract:

A photopolymerizable resinous composition which comprises:
(A) a photocurable prepolymer which is prepared by reacting epoxy resin (a) containing at least two terminated epoxy groups with carboxylic acid (b) containing at least three vinyl linkages and an α,β -unsaturated carboxylic acid (c) and then reacting with polybasic acid anhydride (d) and with a monoeoxide (e) containing one vinyl group,
(B) a photocurable monomer containing one carboxylic acid, which contains at least two vinyl linkages ,
(C) a photocurable monomer containing at least one vinyl group,
(D) a photopolymerization initiator,
(E) a curing agent undergoing a thermal reaction, and
(F) organic solvents.

The composition exhibits photo- and thermocurability, developability with a weak alkaline aqueous solution, a cured article is excellent in electroless gold plating resistance and satisfactory in adhesion soldering heat resistance.

